MMBF5484LT1

Preferred Device

JFET Transistor

N−Channel

Features

- Pb−Free Package is Available

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Drain−Gate Voltage	V_{DG}	25	Vdc
Reverse Gate−Source Voltage	$V_{GS(r)}$	25	Vdc
Forward Gate Current	$I_{G(f)}$	10	mAdc
Continuous Device Dissipation at or Below $T_C = 25°C$ Linear Derating Factor	P_D	200 2.8	mW mW/°C
Storage Channel Temperature Range	T_{stg}	−65 to +150	°C

THERMAL CHARACTERISTICS

| Characteristic	Symbol	Max	Unit
Total Device Dissipation FR−5 Board, (Note 1) $T_A = 25°C$ Derate above 25°C	P_D	225 1.8	mW mW/°C
Thermal Resistance, Junction−to−Ambient	$R_{\theta JA}$	556	°C/W
Junction and Storage Temperature	T_J, T_{stg}	−55 to +150	°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. FR−5 = 1.0 x 0.75 x 0.062 in.

ON Semiconductor®

http://onsemi.com

2 SOURCE
3 GATE
1 DRAIN

SOT−23 (TO−236)
CASE 318
STYLE 10
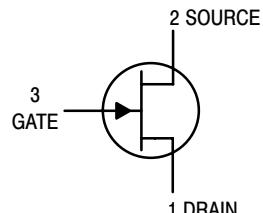
MARKING DIAGRAM

M6B M ▪

1
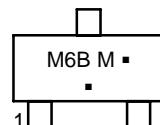
M6B = Device Code
M = Date Code*
▪ = Pb−Free Package
(Note: Microdot may be in either location)
*Date Code orientation and/or overbar may vary depending upon manufacturing location.

Preferred devices are recommended choices for future use and best overall value.

MMBF5484LT1

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Gate–Source Breakdown Voltage (I_G = −1.0 µAdc, V_{DS} = 0)	$V_{(BR)GSS}$	−25	−	Vdc
Gate Reverse Current　　　(V_{GS} = −20 Vdc, V_{DS} = 0)　　　　　　　　　　　　(V_{GS} = −20 Vdc, V_{DS} = 0, T_A = 100°C)	I_{GSS}	−　　−	−1.0　−0.2	nAdc　µAdc
Gate Source Cutoff Voltage (V_{DS} = 15 Vdc, I_D = 10 nAdc)	$V_{GS(off)}$	−0.3	−3.0	Vdc
ON CHARACTERISTICS				
Zero–Gate–Voltage Drain Current (V_{DS} = 15 Vdc, V_{GS} = 0)	I_{DSS}	1.0	5.0	mAdc
SMALL–SIGNAL CHARACTERISTICS				
Forward Transfer Admittance (V_{DS} = 15 Vdc, V_{GS} = 0, f = 1.0 kHz)	$|Y_{fs}|$	3000	6000	µmhos
Output Admittance (V_{DS} = 15 Vdc, V_{GS} = 0, f = 1.0 kHz)	$|y_{os}|$	−	50	µmhos
Input Capacitance (V_{DS} = 15 Vdc, V_{GS} = 0, f = 1.0 MHz)	C_{iss}	−	5.0	pF
Reverse Transfer Capacitance (V_{DS} = 15 Vdc, V_{GS} = 0, f = 10 MHz)	C_{rss}	−	1.0	pF
Output Capacitance (V_{DS} = 15 Vdc, V_{GS} = 0, f = 1.0 MHz)	C_{oss}	−	2.0	pF

COMMON SOURCE CHARACTERISTICS ADMITTANCE PARAMETERS

(V_{DS} = 15 Vdc, $T_{channel}$ = 25°C)
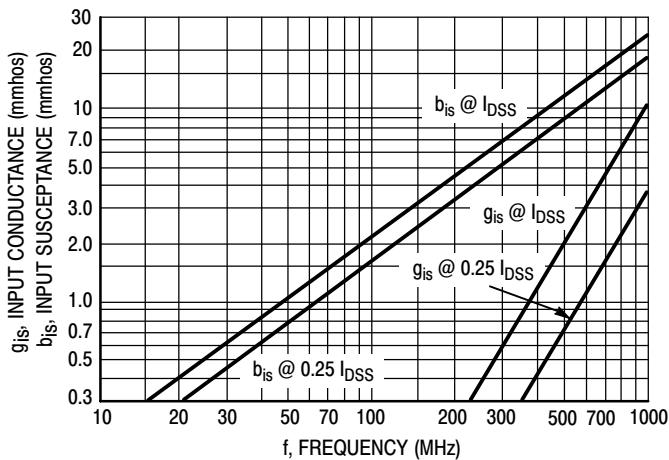

Figure 1. Input Admittance (y_{is})
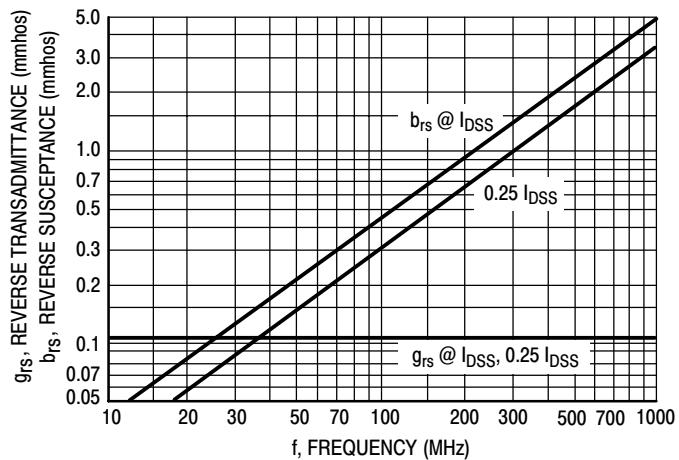

Figure 2. Reverse Transfer Admittance (y_{rs})
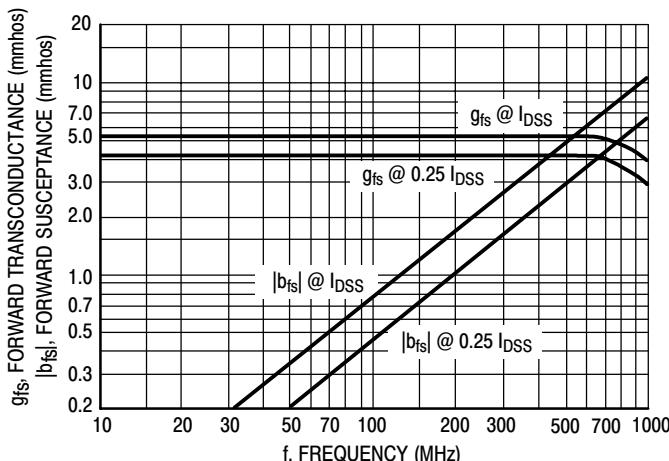
**Figure 3. Forward Transadmittance (y_{fs})**
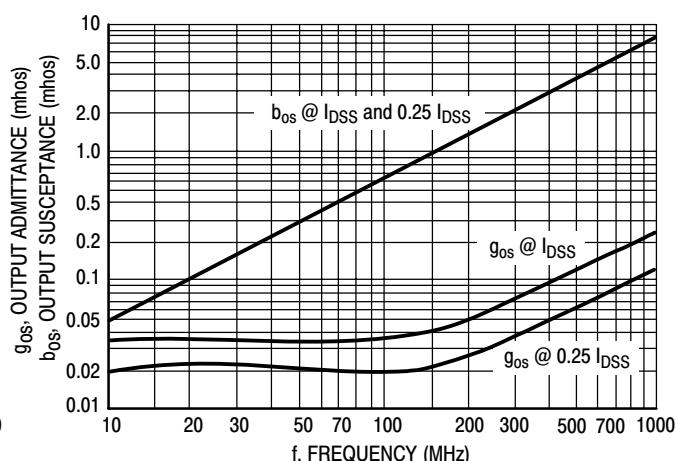
Figure 4. Output Admittance (y_{os})

COMMON SOURCE CHARACTERISTICS
S–PARAMETERS
$(V_{DS} = 15 \text{ Vdc}, T_{channel} = 25°C, \text{Data Points in MHz})$
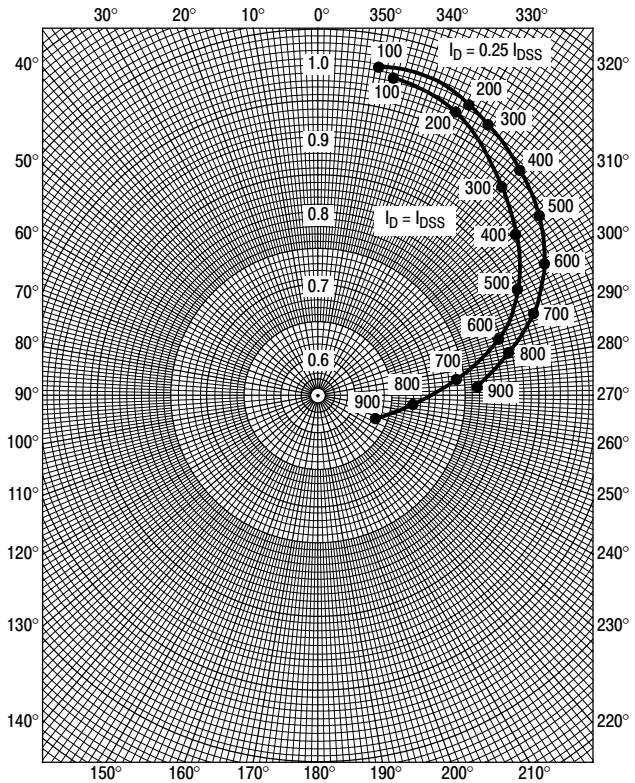

Figure 5. S$_{11s}$
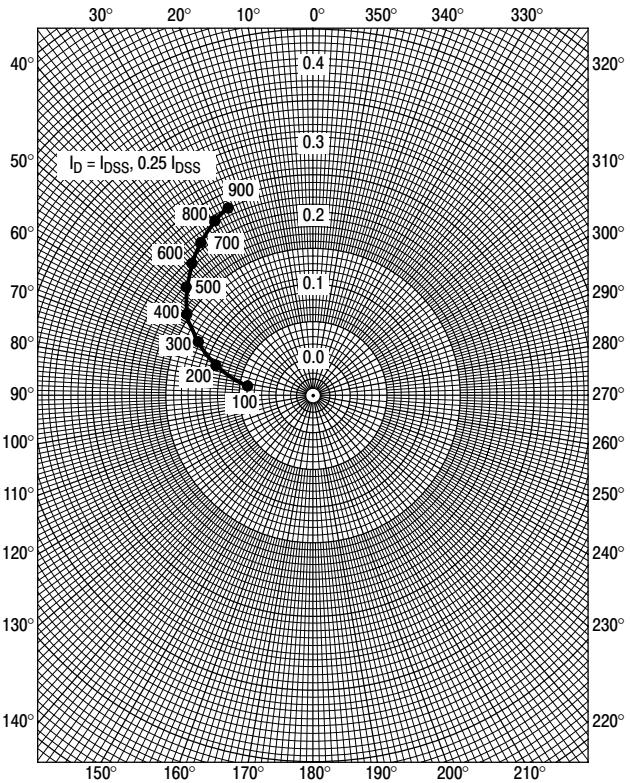
Figure 6. S$_{12s}$
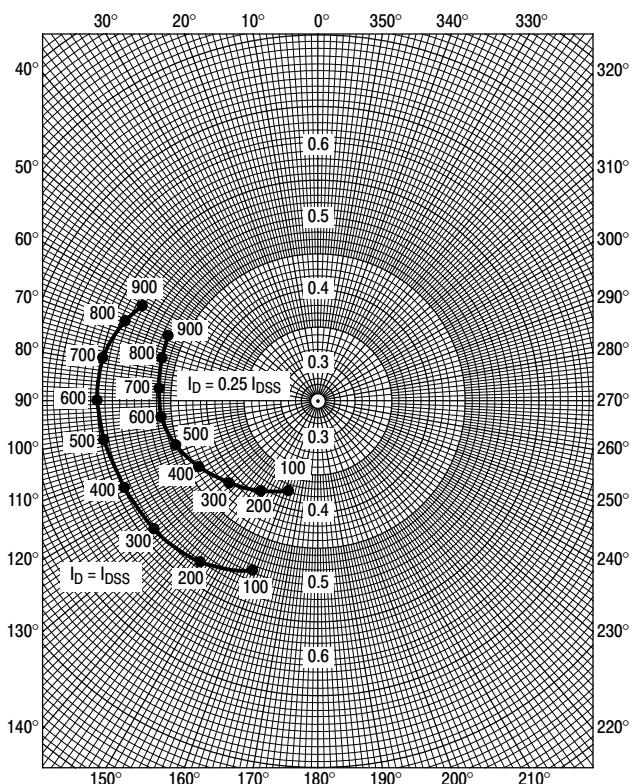
Figure 7. S$_{21s}$
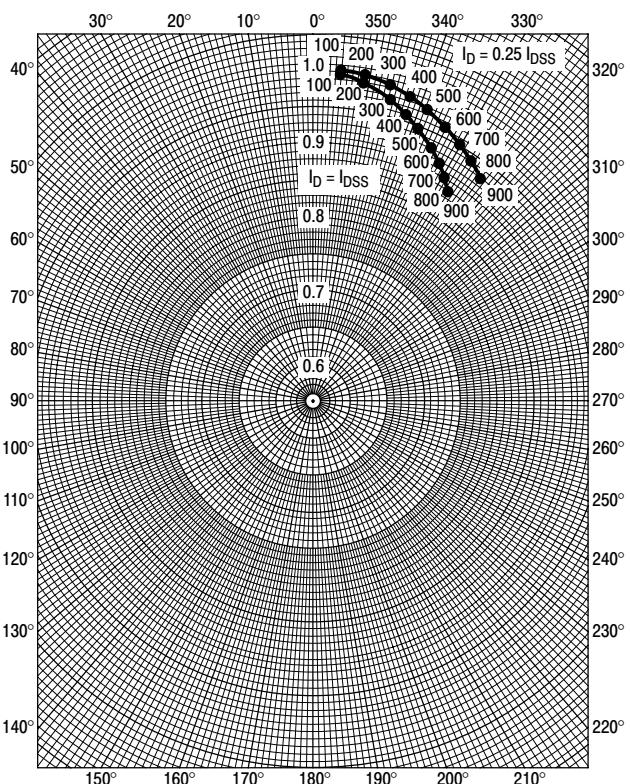
**Figure 8. S$_{22s}$**

COMMON GATE CHARACTERISTICS ADMITTANCE PARAMETERS

(V_{DG} = 15 Vdc, $T_{channel}$ = 25°C)
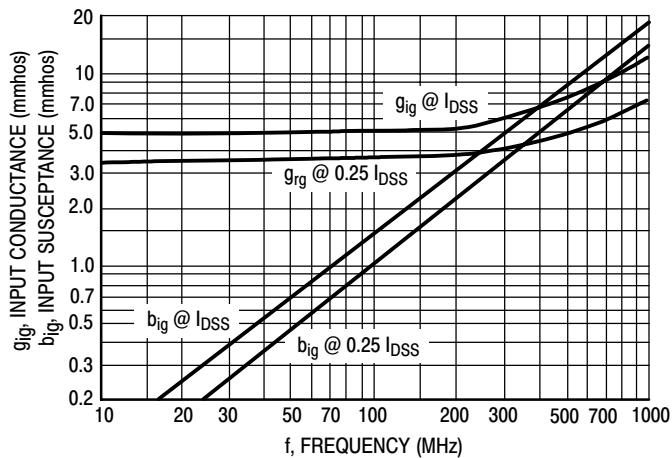
Figure 9. Input Admittance (y_{ig})
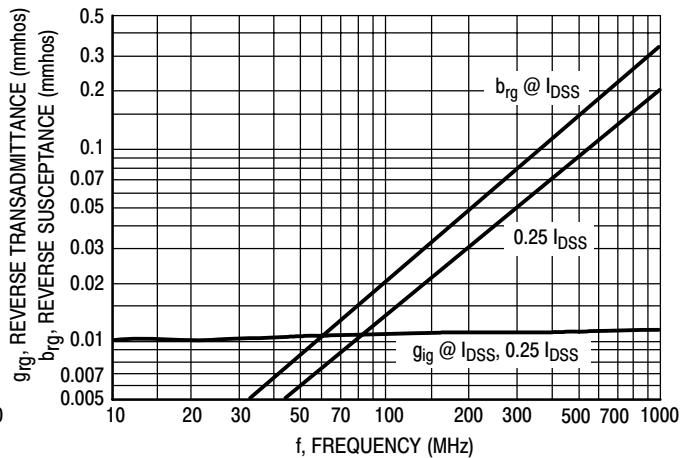
**Figure 10. Reverse Transfer Admittance (y_{rg})**
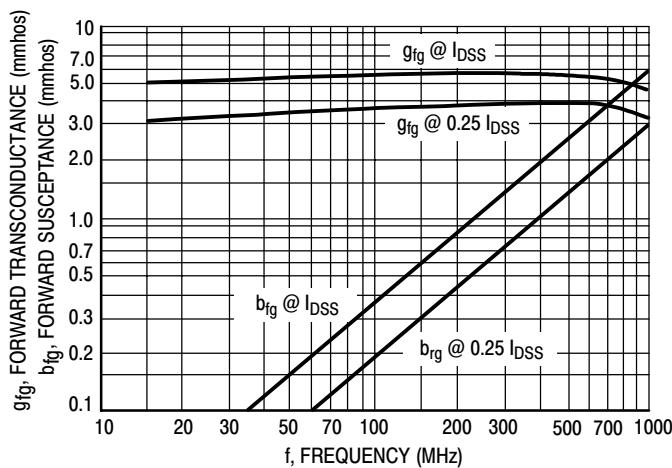
Figure 11. Forward Transfer Admittance (y_{fg})
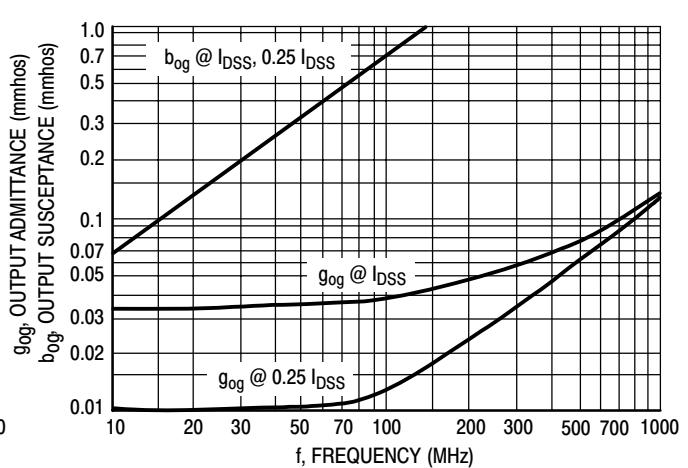
Figure 12. Output Admittance (y_{og})

COMMON GATE CHARACTERISTICS
S–PARAMETERS
(V_{DS} = 15 Vdc, $T_{channel}$ = 25°C, Data Points in MHz)
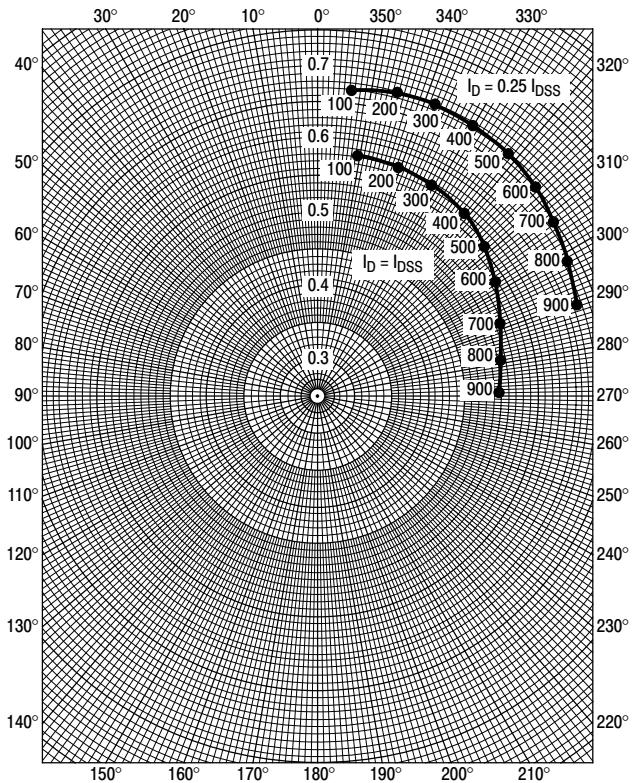
Figure 13. S$_{11g}$
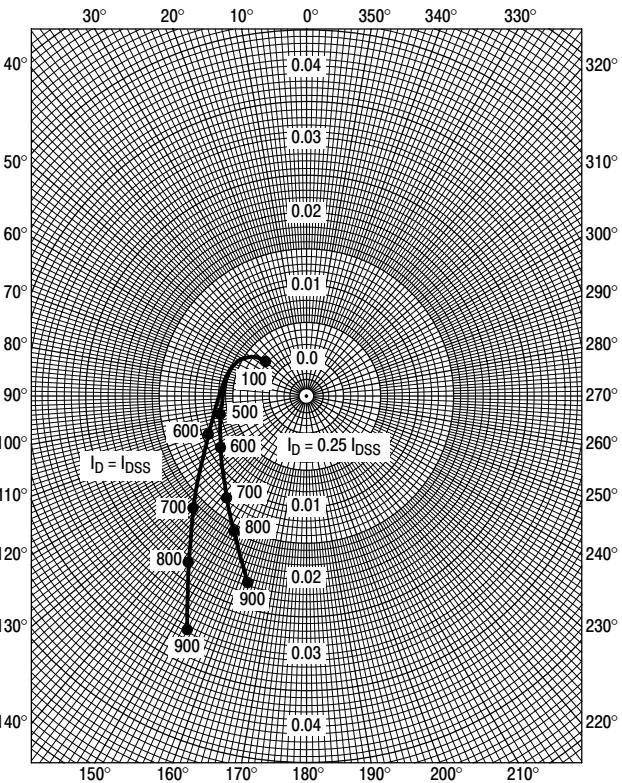
Figure 14. S$_{12g}$
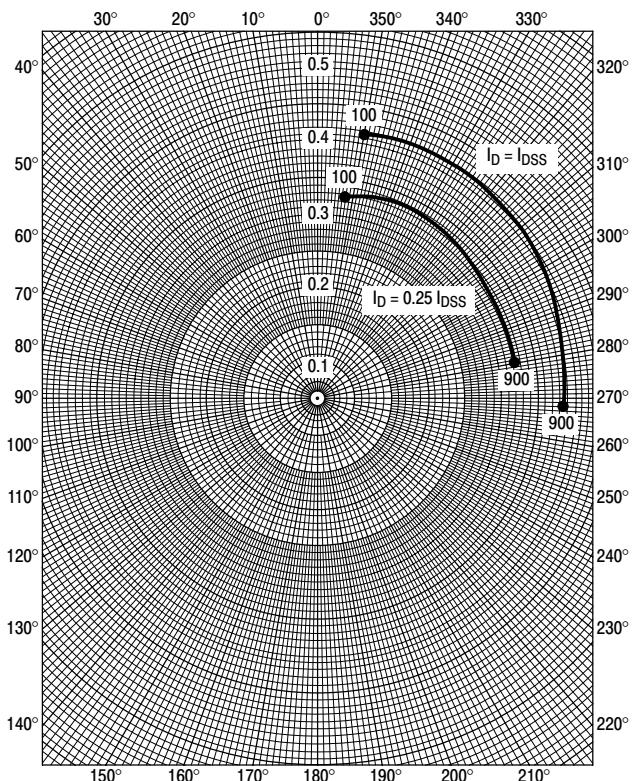
Figure 15. S$_{21g}$
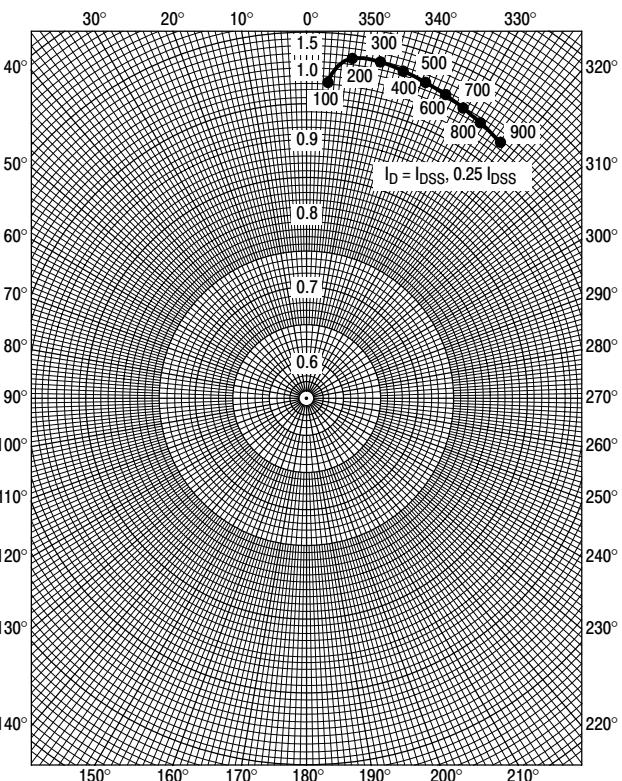
Figure 16. S$_{22g}$

MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

onsemi

SOT−23 (TO−236)
CASE 318
ISSUE AT

DATE 01 MAR 2023

SCALE 4:1

TOP VIEW

DETAIL A

SIDE VIEW

DETAIL A

END VIEW
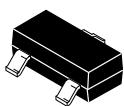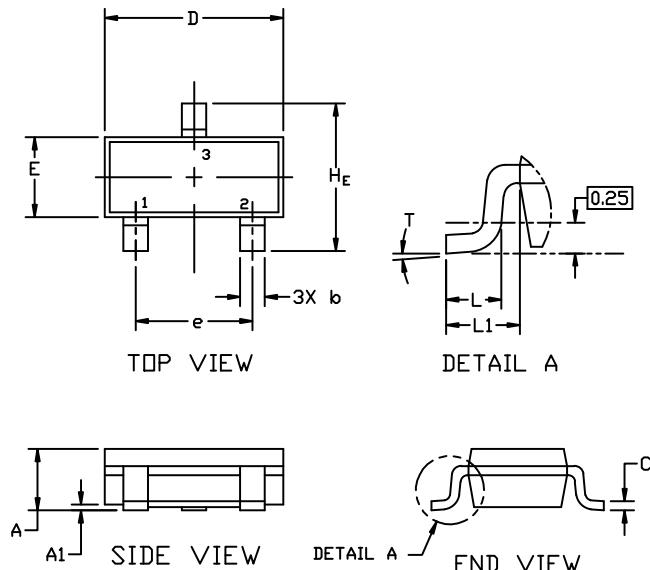
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M,1994.

2. CONTROLLING DIMENSION: MILLIMETERS

3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.

4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

DIM	MILLIMETERS			INCHES		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.89	1.00	1.11	0.035	0.039	0.044
A1	0.01	0.06	0.10	0.000	0.002	0.004
b	0.37	0.44	0.50	0.015	0.017	0.020
c	0.08	0.14	0.20	0.003	0.006	0.008
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
e	1.78	1.90	2.04	0.070	0.075	0.080
L	0.30	0.43	0.55	0.012	0.017	0.022
L1	0.35	0.54	0.69	0.014	0.021	0.027
H_E	2.10	2.40	2.64	0.083	0.094	0.104
T	0°	---	10°	0°	---	10°

GENERIC MARKING DIAGRAM*

XXXM∎
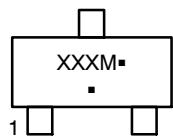
XXX = Specific Device Code
M = Date Code
∎ = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, "G" or microdot "∎", may or may not be present. Some products may not follow the Generic Marking.
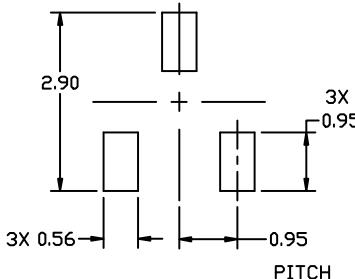
RECOMMENDED
MOUNTING FOOTPRINT

2.90

3X 0.95

3X 0.56

0.95

PITCH

∗ For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

STYLES ON PAGE 2

SOT−23 (TO−236)
CASE 318
ISSUE AT

DATE 01 MAR 2023

STYLE 1 THRU 5:
CANCELLED

STYLE 6:
PIN 1.   BASE
  2.   EMITTER
  3.   COLLECTOR

STYLE 7:
PIN 1.   EMITTER
  2.   BASE
  3.   COLLECTOR

STYLE 8:
PIN 1.   ANODE
  2.   NO CONNECTION
  3.   CATHODE

STYLE 9:
PIN 1.   ANODE
  2.   ANODE
  3.   CATHODE

STYLE 10:
PIN 1.   DRAIN
  2.   SOURCE
  3.   GATE

STYLE 11:
PIN 1.   ANODE
  2.   CATHODE
  3.   CATHODE−ANODE

STYLE 12:
PIN 1.   CATHODE
  2.   CATHODE
  3.   ANODE

STYLE 13:
PIN 1.   SOURCE
  2.   DRAIN
  3.   GATE

STYLE 14:
PIN 1.   CATHODE
  2.   GATE
  3.   ANODE

STYLE 15:
PIN 1.   GATE
  2.   CATHODE
  3.   ANODE

STYLE 16:
PIN 1.   ANODE
  2.   CATHODE
  3.   CATHODE

STYLE 17:
PIN 1.   NO CONNECTION
  2.   ANODE
  3.   CATHODE

STYLE 18:
PIN 1.   NO CONNECTION
  2.   CATHODE
  3.   ANODE

STYLE 19:
PIN 1.   CATHODE
  2.   ANODE
  3.   CATHODE−ANODE

STYLE 20:
PIN 1.   CATHODE
  2.   ANODE
  3.   GATE

STYLE 21:
PIN 1.   GATE
  2.   SOURCE
  3.   DRAIN

STYLE 22:
PIN 1.   RETURN
  2.   OUTPUT
  3.   INPUT

STYLE 23:
PIN 1.   ANODE
  2.   ANODE
  3.   CATHODE

STYLE 24:
PIN 1.   GATE
  2.   DRAIN
  3.   SOURCE

STYLE 25:
PIN 1.   ANODE
  2.   CATHODE
  3.   GATE

STYLE 26:
PIN 1.   CATHODE
  2.   ANODE
  3.   NO CONNECTION

STYLE 27:
PIN 1.   CATHODE
  2.   CATHODE
  3.   CATHODE

STYLE 28:
PIN 1.   ANODE
  2.   ANODE
  3.   ANODE

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DESCRIPTION:	SOT−23 (TO−236)		PAGE 2 OF 2

PUBLICATION ORDERING INFORMATION

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